ABSTRACT OF THE DISCLOSURE

For processing a resin sealed lead frame according to the present invention, processing means (101, 102, 103, 104) related to a plurality of steps used for processing a lead of resin sealed lead frame (A) are separated as modules and detachably connected. Only the processing means as the modules related to the steps actually required for lead processing of the resin sealed lead frame are selected and connected. The resin sealed lead frame is sequentially fed to the processing means as the modules for lead processing of the resin sealed lead frame. Thus, a method of processing the resin sealed lead frame and an apparatus therefor which are capable of coping with a change in the type of the operation and the production volume are provided for lead processing of the resin sealed lead frame.

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